





























MEMS Technologies and Optical Element Size							
1 c Optical	m 1 mr	n	100 µm	10 µm	1 µn	n	
Size	Scanning display	Mirror-based	OADM	Projection		Micro-	
Applications	3D-MEI OXC	MS 2D MEMS Switch	WSS Gain equalizer Dispersion compensator	display 2x2 Switches VOA	Diffractive MEMS	resonators Photonic Crystals	
Main Fabrication Technologies	Bulk-Micromachining (Single Crystalline Si, DRIE, Wafer Bonding)		Surface-Micromachining (Poly-Si, Al)			Nano- Fabrication	
Main Actuation Mechanisms	Electromagnetic Actuation	Electrostatic Actuation					
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SUMMARY	
 Tremendous progresses have been made in MEMS devices and manufacturing Micro-optics Packaging Control 	
 New trends in Optical MEMS Integration Higher level of integration, less free-space align MEMS-PLC integration MEMS-nanophotonics integration Electronics integration Single-chip optical MEMS system 	iment
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